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Dear Editor

Re: Paper ID 452

Title: Residual stress in polycrystalline thin Cr films deposited on fused silica substrates

We would like to take this opportunity to thank the reviewers for their contributions and comments to the manuscript. The manuscripts was edited and corrected according to the reviewer's comments however I want to bring to your attention the following:

1. In figure 2, a new graph has been added which was not there from the previous version as requested by the reviewer that a θ - 2θ XRD scan of one of the samples must be added.
2. In section 3 of results, the reviewer proposed that we should give some mechanism which explains why 40nm sample doesn't exhibits the same trend. This we tried to explain by the fact that the T_N of the same sample also doesn't follow the trend which links the two, however the cause of the high stress it was said to be due to the film thickness and coefficient of thermal expansion.

We trust that our manuscript may now be re-considered for publication.

Thank you

Yours sincerely

Zwivhuya Patience Mudau